



Product Change Notification - GBNG-23KQCL340

Date:

12 Nov 2018

Product Category:

8-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3600, 3600.001-3600.003 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected Atmel products of the 35.4K, 35.5K and 35.8K wafer technologies available in 40L PDIP, 20L PDIP, 8L PDIP and 28L SPDIP packages.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected Atmel products of the 35.4K, 35.5K and 35.8K wafer technologies available in 40L PDIP, 20L PDIP, 8L PDIP and 28L SPDIP packages.

Pre Change:

Using gold (Au) bond wire.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire material	Au	CuPdAu
Die attach material	CRM-1064L	CRM-1064L
Molding compound material	GE800	GE800
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress



Estimated Qualification Completion Date:

December 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2018					December 2018			
Workweek	44	45	46	47	48	49	50	51	52
Initial PCN Issue Date			X						
Qual Report Availability									X
Final PCN Issue Date									X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

November 12, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-23KQCL340_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

GBNG-23K(3600.001-: 35.5K and 20L PDIP 8L PDIP and 28L SPDIP packages.

Affected Catalog Part Numbers(CPN)

AT89LP2052-20PU
AT89LP4052-20PU
AT89S2051-24PU
AT89S4051-24PU
ATMEGA1284P-PU
ATMEGA1284-PU
ATMEGA328P-PU
ATTINY2313-20PU
ATTINY2313A-PU
ATTINY2313V-10PU
ATTINY26-16PU
ATTINY261A-PU
ATTINY26L-8PU
ATTINY4313-PU
ATTINY461-20PU
ATTINY461A-PU
ATTINY461V-10PU
ATTINY861-20PU
ATTINY861A-PU
ATTINY861V-10PU